

ABSTRACT OF THE DISCLOSURE

POLISHING METHOD AND POLISHING APPARATUS

5 A substrate polishing method capable of reducing an influence of variation in
spectrum of reflected light from a substrate, such as a wafer, and determining an accurate
film thickness is disclosed. The method includes: polishing a surface of a substrate by
pressing the substrate against a polishing pad on a rotating polishing table; producing a
spectrum of reflected light from the surface of the substrate each time the polishing table
10 makes one rotation; creating a three-dimensional data containing a plurality of spectra
arranged along polishing time; and determining a film thickness of the substrate based on the
three-dimensional data.

FIG. 9

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